

CB TEST CERTIFICATE CERTIFICAT D'ESSAI OCProduct
Produit

Integrated Circuit with X-capacitor discharge function

Name and address of the applicant
Nom et adresse du demandeurTexas Instruments Incorporated
12500 TI Boulevard, MS K1-20
Dallas, TX 75243
USAName and address of the manufacturer
Nom et adresse du fabricantTexas Instruments Incorporated
12500 TI Boulevard, MS K1-20
Dallas, TX 75243
USAName and address of the factory
Nom et adresse de l'usineTexas Instruments Malaysia Sdn Bhd
No. 1, Lorong Enggang 33 Ampang/Ulu Klang
Kuala Lumpur, 54200
MalaysiaNote: When more than one factory, please report on page 2
Note: Lorsque il y a plus d'une usine, veuillez utiliser la deuxième page Additional information on page 2Ratings and principal characteristics
Valeurs nominales et caractéristiques principales264V AC maximum
(Applicable for use with mains supply 85-264Vac, 47-63Hz)Trademark (if any)
Marque de fabrique (si elle existe)Type of Manufacturer's Testing Laboratories used
Type de programme du laboratoire d'essais constructeur

UCC25630

Model / Type Ref.
Ref. De typeAdditional information (if necessary may also be
reported on page 2)
Les informations complémentaires (si nécessaire,
peuvent être indiqués sur la deuxième pageComponent for building-in. May be provided with additional suffix
characters that do not affect the safety function of the component. Additional information on page 2A sample of the product was tested and found
to be in conformity with
Un échantillon de ce produit a été essayé et a été
considéré conforme à la

IEC 60065:2014

As shown in the Test Report Ref. No. which forms part
of this Certificate

325705

Comme indiqué dans le Rapport des essais numéro de
référence qui constitue partie de ce CertificatThis CB Test Certificate is issued by the National Certification Body
Ce Certificat de essai OC est établi par l'Organisme **National de Certification**Gaustadalléen 30
NO-0373 Oslo, Norway

Date: 01-09-2017

Signature: Okhyun Jeon
Certification Department

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